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In the Claims:

Claims 1-32 (canceled).

Claim 33 (currently amended): A composite structure in an IC chip, said composite structure comprising:

a first metal pad structure comprising a plurality of segments of a first interconnect metal, at least one of said plurality of segments of said first interconnect metal extending along at least one side of said first metal pad structure;

a first via pad structure below said first metal pad structure, said first via pad structure comprising a plurality of segments of a first via metal and a first plurality of dielectric fillers, each of said first plurality of dielectric fillers being situated between two of said plurality of segments of said first via metal, at least one of said plurality of segments of said first via metal being in contact with said at least one of said plurality of segments of said first interconnect metal ~~contacting said first interconnect metal~~, at least two of said plurality of segments of said first via metal being connected.

Claim 34 (previously presented): The composite structure of claim 33 wherein said first interconnect metal is selected from the group consisting of copper and aluminum.